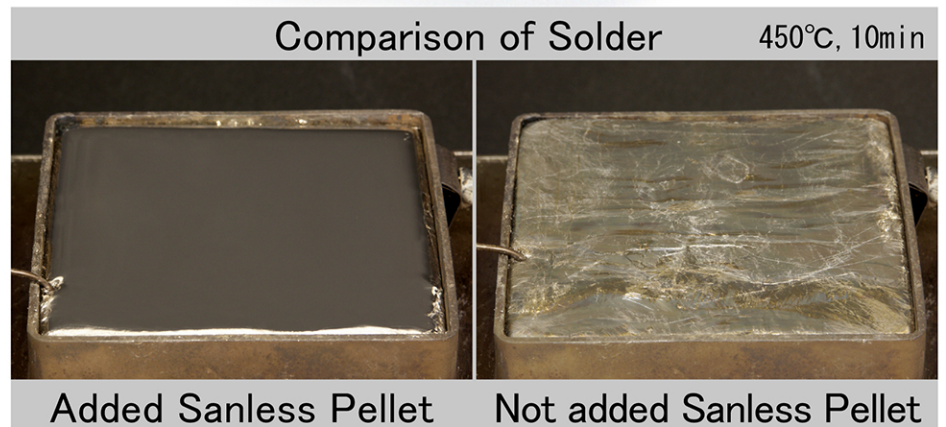
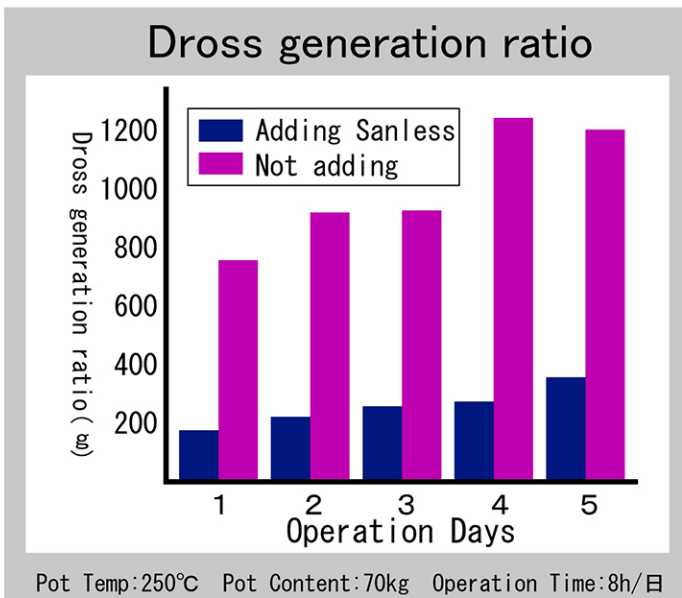


# Control Oxidation in Solder Bath

Anti Oxidation Agent for Lead Free Solder  
**SANLESS PELLET 100**

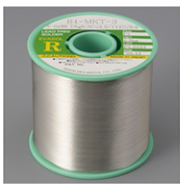
By adding Sanless Pellet in melting solder pot, can make clear layer and reduce oxidization ratio, by making clear layer in solder pot.



# Low Ag & Low Cost Solder

SAC305 is common alloy for lead free but by increasing of Ag price, users are looking for another alloy. Ishikawa Metal success to keeping excellent wettability by using low silver alloy.

Low Ag& Low Cost Flux cored solder wire  
**R4-MKT-3**

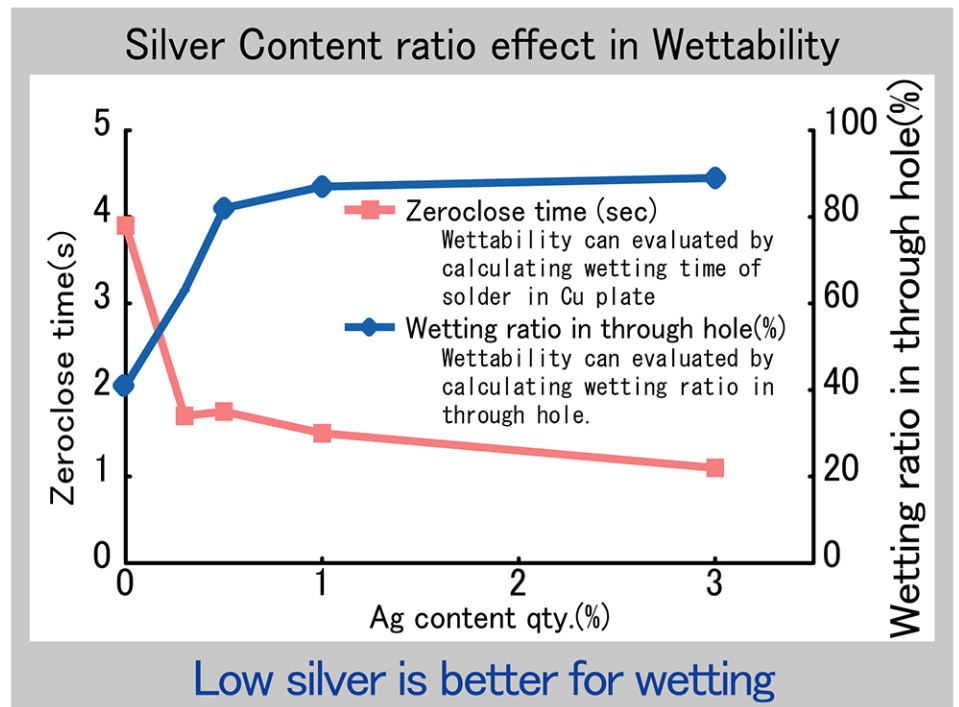


- Alloy (Sn99-Cu0.7-Ag0.3%)
- Excellent Wettability and less spitting
- Less Smoke & Smell

Low Ag & Low Cost Solder Paste  
**R4-8850-UG**



- SAlloy (Sn99-Cu0.7-Ag0.3%)
- Stable Wettability
- Less Chip Side Balls



Ref: JEITA Report (2007)